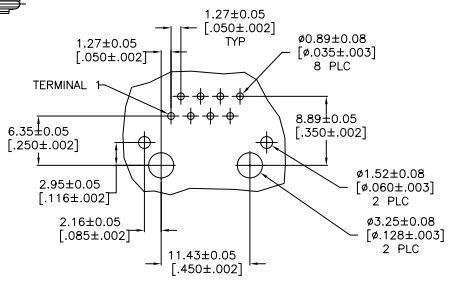
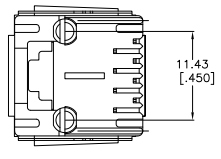
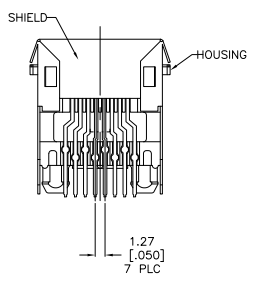
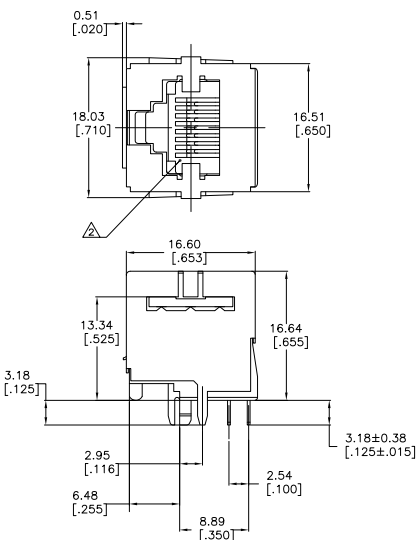
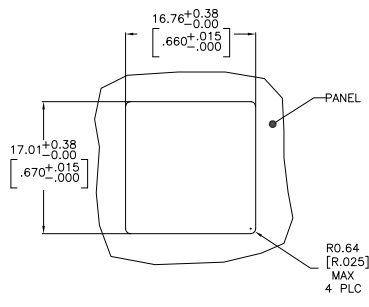


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REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00	REVISED PER EDD-11-604836	11MMR11	RC	HMR



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
 COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

1. MATERIAL:
 HOUSING - POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS - 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27 μ m[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81 μ m[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MIN THICK NICKEL UNDERPLATE
 SHIELD - COPPER ZINC ALLOY PLATED WITH 3.0 μ m [.000120] MIN THICK REFLOWED TIN.

CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

5406436-1
 PART NO.

THIS DRAWING IS A CONTROLLED DOCUMENT.		APPROVED FOR RELEASE	DATE	BY	APP
INCHES	MM	ALCOBETA	0000	000000	
DESIGNED BY	REVIEWED BY	DATE	BY	APP	
108-1163	114-2048	108-1163	114-2048		
SEE NOTE 1	SEE NOTE 1	CUSTOMER DRAWING	100779	5406436	